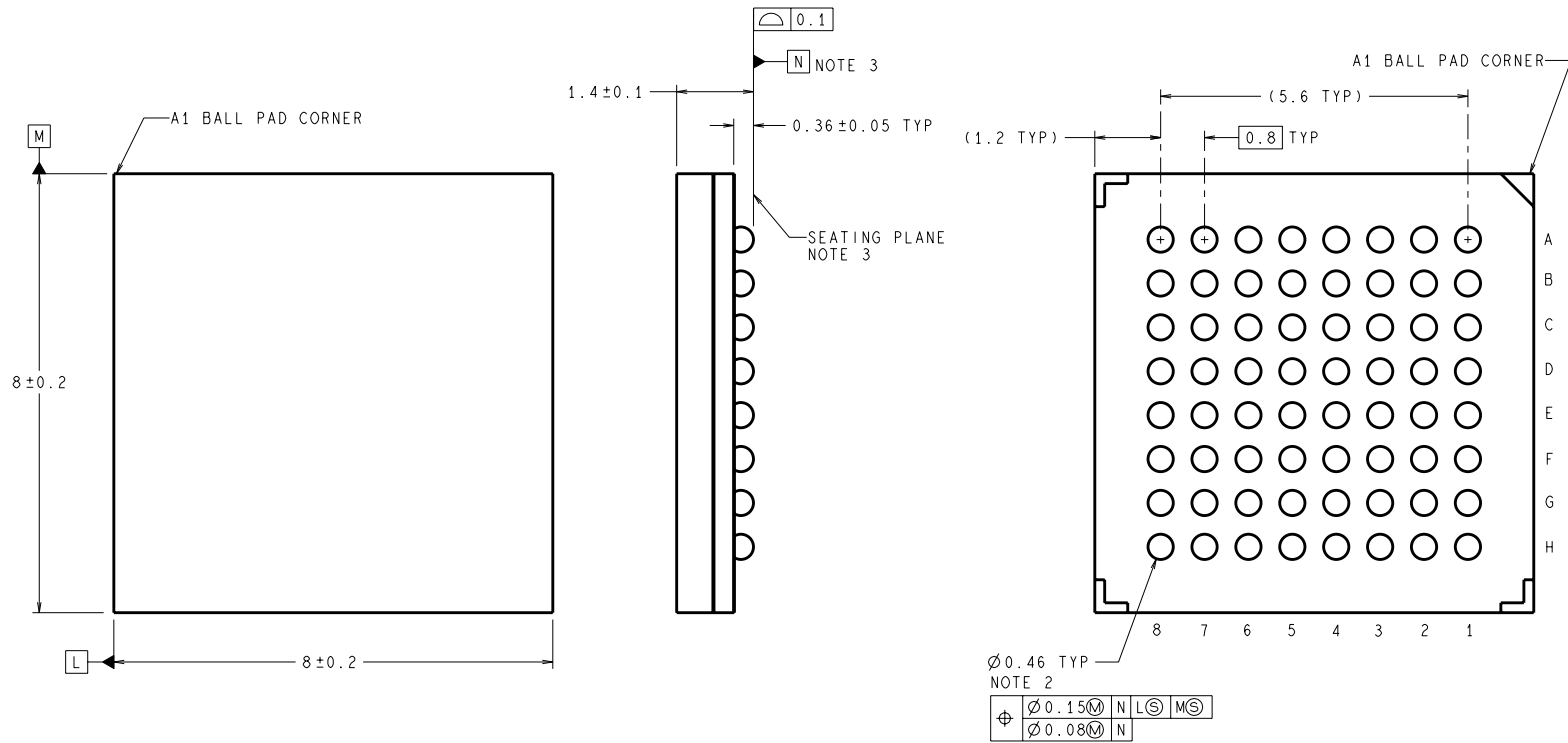


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11990	05/08/1998	TL/SL
B	REVISE TITLE	12174	03/18/1999	MS/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. NO JEDEC REGISTRATION AS OF MAY 1998.

$\varnothing 0.46$ TYP
NOTE 2

$\varnothing 0.15$	N	L	M
$\varnothing 0.08$	N		

APPROVALS		DATE	National Semiconductor	
DRAWN T. LEQUANG		05/08/1998	2900 Semiconductor dr., Santa Clara, CA 95052-8090	
DFTG. CHK.			FBGA, PLASTIC, LAMINATED, 0.8mm PITCH, 8 X 8 X 1.4mm, 64 BALL	
ENGR. CHK.				
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		N/A	C	(SC)MKT-SLC64A
INCH (MM)		DO NOT SCALE DRAWING		REV B
		SHEET 1 of 1		